

Comment	Description	Designator	Footprint	LibRef	Quantity
C1005X7R1H104M	CAP, CERM, 0.1uF, 50V, +/-20%, C0G/NP0, 0402	C1, C7, C16	0402L	C1005X7R1H104M	3
GRM21BR61A476ME15	CAP, CERM, 47uF, 10V, +/-20%, X5R, 0805	C2, C3, C19, C20	0805L	GRM21BR61A476ME15	4
C2012X6S1C106MT	CAP, CERM, 10uF, 16V, +/-10%, X6S, 0805	C4, C5, C6, C17, C18	0805L	C2012X6S1C106MT	5
GRM188R60J475KE19D	CAP, CERM, 4.7uF, 6.3V, +/-10%, X5R, 0603	C8, C9	0603L	GRM188R60J475KE19D	2
GRM1555C1H151JA01D	CAP, CERM, 150pF, 50V, +/-5%, C0G/NP0, 0402	C10	0402L	GRM1555C1H151JA01D	1
GCM155R71H223KA55D	CAP, CERM, 0.022uF, 50V, +/-10%, C0G/NP0, 0402	C11	0402L	GCM155R71H223KA55D	1
C1005X7R1C473K	CAP, CERM, 0.047uF, 16V, +/-10%, X7R, 0402	C12	0402L	C1005X7R1C473K	1
GRM188R71E105KA12D	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603	C13, C15	0603L	GRM188R71E105KA12D	2
C1005X7R1C103K	CAP, CERM, 0.01uF, 16V, +/-10%, X7R, 0402	C14	0402L	C1005X7R1C103K	1
ED555/2DS	Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	J1, J2	TERM_BLK_ED555-2DS	ED555/2DS	2
PEC02SAAN	Header, 100mil, 2x1, Tin plated, TH	J3, J4, J5, J6	CONN_PEC02SAAN	PEC02SAAN	4
NPIM103B3R3MTRF	Inductor, Shielded Drum Core, Powdered Iron, 3.3uH, 250mA	L1	NPIM103B3R3MTRF	74437368033	1
744025001	Inductor, Shielded Drum Core, Ferrite, 1.2uH, 250mA	L2	WE-TPC_2828	744025001	1
TR-CSD87381P	MOSFET, Synchronous Buck NexFETPower Block, 1.5A, 30V	Q1	LGA-2.5X3MM	TR-CSD87381P	1
CRCW040215K0FKED	RES, 15.0k ohm, 1%, 0.063W, 0402	R1	0402L	CRCW040215K0FKED	1
CRCW040213K7FKED	RES, 13.7k ohm, 1%, 0.063W, 0402	R2	0402L	CRCW040213K7FKED	1
CRCW04024K75FKED	RES, 4.75k ohm, 1%, 0.063W, 0402	R3	0402L	CRCW04024K75FKED	1
CRCW04023K01FKED	RES, 3.01k ohm, 1%, 0.063W, 0402	R4	0402L	CRCW04023K01FKED	1
CRCW040210K0FKED	RES, 10.0k ohm, 1%, 0.063W, 0402	R5, R13, R16	0402L	CRCW040210K0FKED	3
RC0402JR-070RL	RES, 0 ohm, 5%, 0.063W, 0402	R6, R7	0402L	RC0402JR-070RL	2
CRCW040249R9FKED	RES, 49.9 ohm, 1%, 0.063W, 0402	R8	0402L	CRCW040249R9FKED	1
CRCW0402100KFKED	RES, 100k ohm, 1%, 0.063W, 0402	R9	0402L	CRCW0402100KFKED	1
CRCW040263K4FKED	RES, 63.4k ohm, 1%, 0.063W, 0402	R10	0402L	CRCW040263K4FKED	1
CRCW04027K50FKED	RES, 7.50k ohm, 1%, 0.063W, 0402	R11	0402L	CRCW04027K50FKED	1
CRCW040295K3FKED	RES, 95.3k ohm, 1%, 0.063W, 0402	R12	0402L	CRCW040295K3FKED	1
CRCW040210R0FKED	RES, 10.0 ohm, 1%, 0.063W, 0402	R14, R15	0402L	CRCW040210R0FKED	2
CRCW04021K00FKED	RES, 1.00k ohm, 1%, 0.063W, 0402	R17	0402L	CRCW04021K00FKED	1
ERT-J0ER103H	Thermistor NTC, 10k ohm, 3%, 0402	RT1	0402L	ERT-J0ER103H	1
TPS43061RTE	Low Quiescent Current Synchronous Boost DC-DC Converter	U1	RTE0016G	TPS43061RTE	1
LM2904M	Low Power Dual Op Amp	U2	M08A_N	LM2904M	1
INA213BIDCK	Voltage Output, High or Low Side Measurement	U3	DCK0006A_N	INA214BIDCK	1

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